

ABSTRACT

The present invention disclosed an electroplating apparatus for non-circular substrate, comprising a central electrode area, a peripheral electrode area, a power supply unit and a control device. The size of the central electrode area is the inscribed circle of the non-circular substrate, and the central electrode is arranged in the central electrode area. The peripheral electrode area surrounds the central electrode area. The peripheral size of the peripheral electrode area is the circumscribed circle of the non-circular substrate. The peripheral electrode area is provided with closely arranged point electrodes, and the point electrodes fill the peripheral electrode area. The power supply unit supply power to the central electrode and the point electrodes. The control device is connected between the power supply unit, the central electrode and the point electrodes and controls the on-off of the central electrode and the point electrodes. The control device tracks the rotating position of the substrate, so that the electrodes in the central electrode area and the peripheral electrode area covered by the substrate will be turned on and the electrodes not covered by the substrate will be turned off. The present invention also disclosed an electroplating method for the non-circular substrate.